

LINQSOL™ EMC-G836

Black epoxy molding compound



- Green epoxy molding compound
- Designed for Quad Flat No Leads (QFN) and Quad Flat (QFP) packages
- Designed to satisfy JEDEC MSL 3 reliability

LINQSOL™ EMC-G836 is a halogen-free epoxy molding compound specifically developed for the encapsulation of Quad Flat No Leads (QFN), Quad Flat (QFP) packages and other thin, high-density packages, such as BGA TF card (microSD). Its wide gel time provides a better processing window, required for QFN and QFP molding. **LINQSOL™ EMC-G836** has high spiral flow that meets higher flowability requirements. Additionally, with a UL 94 V-0 flammability rating and low water absorption, **EMC-G836** guarantees excellent performance and outstanding reliability. This product is deliberately formulated without the inclusion of substances prohibited by the European Union RoHS and REACH.

Overall, **LINQSOL™ EMC-G836** seamlessly integrates advanced material properties, safety compliance, and superior performance to deliver a reliable solution for semiconductor device encapsulation.

Specifications

Property	Value	Unit
General Properties		
Color	Black	–
Filler content	88	%
Filler shape	Spherical	–
Filler sieving size	75	µm
Specific gravity	2.0 ±0.02	–
Spiral flow at 175 °C	149 ±5%	cm
Melt viscosity at 175 °C	18000 ±10%	cP
Chemical Properties		
Ion content		
Chloride (Cl ⁻) concentration	<10	ppm
Sodium (Na ⁺) concentration	<15	ppm
Moisture absorption at PCT24h	≤0.25	%
pH of extract	5–7	–
Mechanical Properties		
Flexural strength at 25 °C	160 ±5%	MPa
Flexural modulus at 25 °C	25 ±5%	GPa
Mold shrinkage	0.18	%
Poisson's ratio at 25 °C	0.3	–

Europe

Industrieweg 15E,
1566JN Assendelft
The Netherlands
Phone: +31 (20) 893 2224
Email: info@caplinq.com

Canada

80 Sirocco Crescent
Ottawa ON, K2S 2C9
Canada
Phone: +1 (613) 482-2215
Email: info@caplinq.com



North America

36927 Schoolcraft Rd
Livonia, MI 48150
United states
Phone: +1 (313) 558-8243
Email: info@caplinq.com

South East Asia

S-08-07 Persiaran Triangle
B Lepas, Penang 11900
Malaysia
Phone: +60(12)4302223
Email: info@caplinq.com

Property	Value	Unit
Electrical Properties		
Dielectric constant at 1 MHz	3.8	–
Dissipation factor at 1 MHz	0.005	–
Thermal Properties		
Glass transition temperature	120 $\pm$ 5	°C
Coefficient of thermal expansion, α_1	9	ppm/°C
Coefficient of thermal expansion, α_2	37	ppm/°C
Gel time at 175°C	36 $\pm$ 5	s
Thermal conductivity	0.92 $\pm$ 0.02	W/mK
Flammability rating	V-0	UL-94

Recommended mold parameters

Parameters	Value	Unit
Molding temperature	170–180	°C
Transfer pressure	70–150	kg _f /cm ²
Transfer time	8–25	s
Cure time at 175°C	100–180	s
Post mold cure time at 175°C	4–8	h

The curing conditions provided are recommended guidelines based on typical laboratory results. Actual curing parameters should be defined and validated by the user to ensure compatibility with specific materials, part geometries, and end-use requirements. It is the user's responsibility to optimize and confirm curing conditions that meet their performance and quality standards.

Processing Instructions

- Before use, let **LINQSOL™ EMC-G836** reach room temperature (23 °C $\pm$ 5) for 16 hours. Keep the bag unopened and stored in a dry location with a relative humidity of $\leq$ 50% during thawing to prevent moisture contamination.
- Use the materials within 24 hours after removing the container from cold storage.

Storage and Handling

LINQSOL™ EMC-G836 is available in pressed pellets in a wide range of sizes to meet specific customer needs. To ensure product integrity, keep it away from oxidizing materials. For long-term storage, maintain a cold environment. The shelf life when stored below 5 °C is 183 days.

The technical information presented in this document is provided for reference only and does not constitute a guarantee of specific properties or performance. Actual results may vary depending on individual conditions and application methods. Users are strongly advised to perform their own testing and validation to determine suitability for their intended use and compliance with relevant regulations.

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